

2SB1722G

Silicon PNP epitaxial planar type

For high breakdown voltage low-frequency amplification

■ Features

- High collector-emitter voltage (Base open) V_{CEO}
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Package

- Code
SSMini3-F3
- Marking Symbol: 4R
- Pin Name
 1. Base
 2. Emitter
 3. Collector

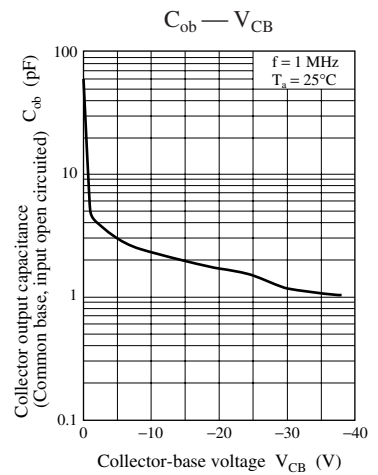
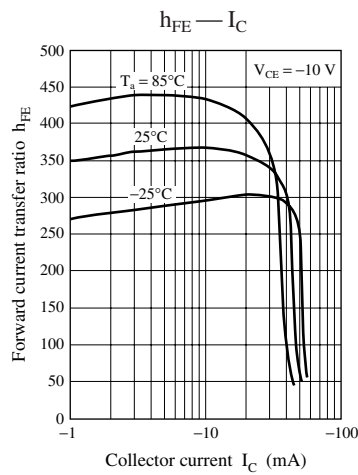
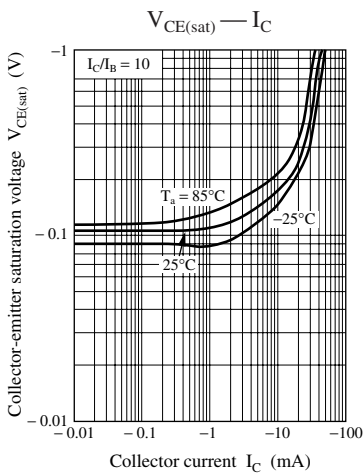
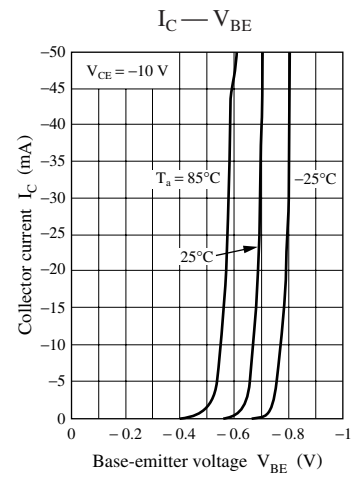
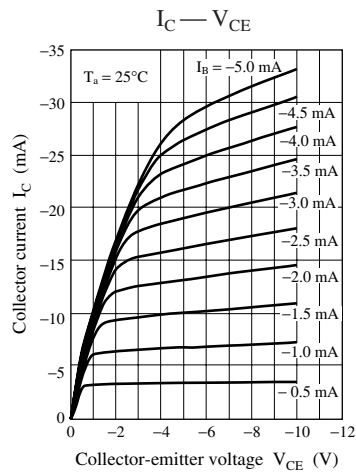
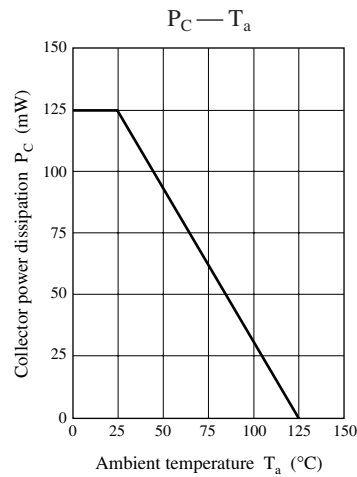
■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	-100	V
Collector-emitter voltage (Base open)	V_{CEO}	-100	V
Emitter-base voltage (Collector open)	V_{EBO}	-5	V
Collector current	I_C	-20	mA
Peak collector current	I_{CP}	-50	mA
Collector power dissipation	P_C	125	mW
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

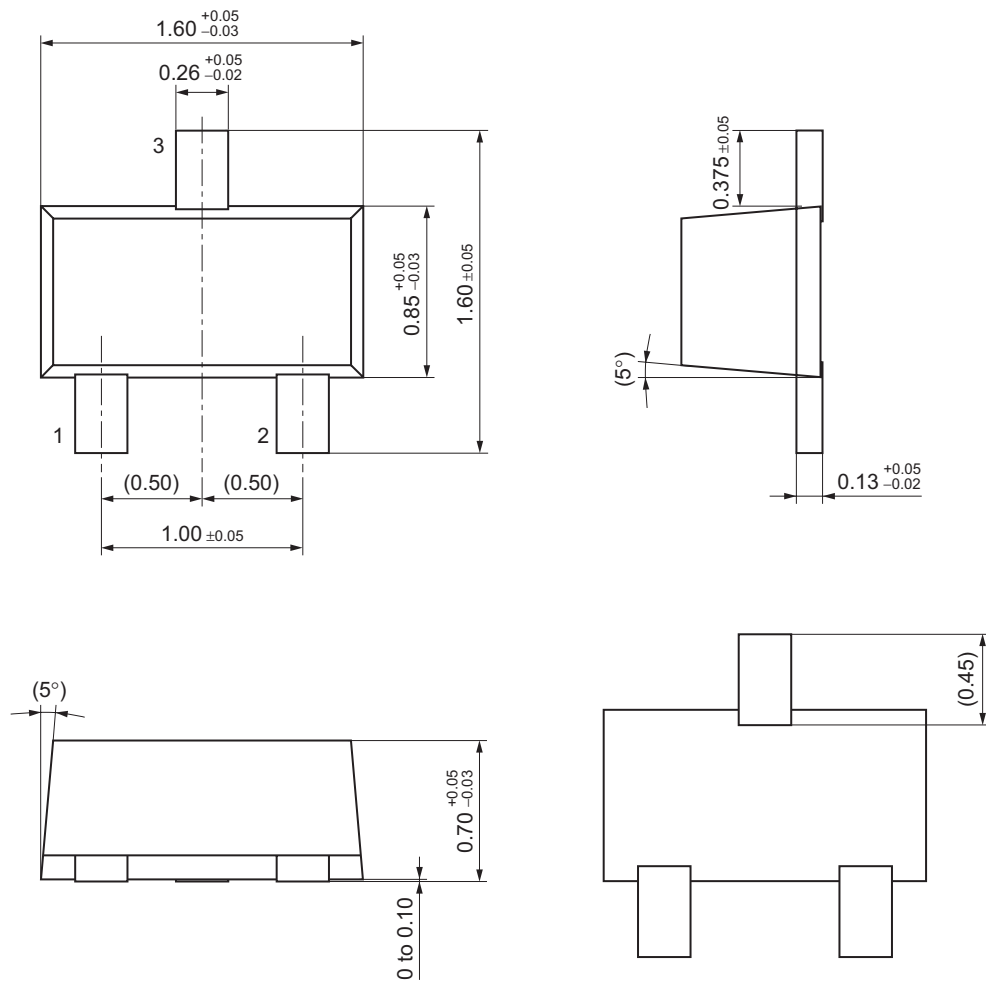
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = -10\ \mu\text{A}$, $I_E = 0$	-100			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -1\ \text{mA}$, $I_B = 0$	-100			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10\ \mu\text{A}$, $I_C = 0$	-5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -50\ \text{V}$, $I_E = 0$			-100	nA
Collector-emitter cut-off current (Base open)	I_{CEO}	$V_{CE} = -50\ \text{V}$, $I_B = 0$			-1	μA
Forward current transfer ratio	h_{FE}	$V_{CE} = -10\ \text{V}$, $I_C = -2\ \text{mA}$	200		700	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -10\ \text{mA}$, $I_B = -1\ \text{mA}$			-0.3	V
Transition frequency	f_T	$V_{CB} = -5\ \text{V}$, $I_E = 2\ \text{mA}$, $f = 200\ \text{MHz}$		200		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



SSMini3-F3

Unit: mm



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